



Description

The MDD1951RH uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



TO-252-2L

General Features

 $V_{DS} = 60V I_{D} = 20 A$

 $R_{DS(ON)} < 32m\Omega$ @ $V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply

PIN1 G PIN3 S

N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
MDD1951RH	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	Drain-Source Voltage 60	
Vgs	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	20	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	10	А
Ірм	Pulsed Drain Current ²	80	А
EAS	Single Pulse Avalanche Energy ³	38	mJ
P _D @T _C =25°C	Total Power Dissipation ⁴	34.7	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range -55 to 150		°C



Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics				•				
Drain-Source Breakdown Voltage		V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	60	-	_	V	
Gate-Body Leakage Current		Igss	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA	
Zero Gate Voltage Drain Current	TJ=25℃		V _{DS} = 60V, V _{GS} = 0V	-	-	1	μА	
	TJ=100℃	- I _{DSS}		-	-	100		
Gate-Threshold Voltage		V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.2	1.7	2.5	V	
Dunin Course on Besistance	-4	_	V _{GS} = 10V, I _D = 10A	-	25	32		
Drain-Source on-Resistance ⁴		R _{DS(on)}	V _{GS} = 4.5V, I _D = 5A	-	31.5	40	mΩ	
Forward Transconductance ⁴		G fs	V _{DS} = 5V, I _D = 10A	-	15.5	-	S	
Dynamic Characteristic	:s ⁵							
Input Capacitance		C _{iss}		-	1355	-	pF	
Output Capacitance		Coss	V_{DS} = 30V, V_{GS} =0V, f =1MHz	-	60	-		
Reverse Transfer Capacitance		C _{rss}	_	-	49	-		
Gate Resistance		R _G	f=1MHz	-	1.2	-	Ω	
Switching Characteristi	ics ⁵							
Total Gate Charge		Qg		-	22	-	nC	
Gate-Source Charge		Q _{gs}	$V_{GS} = 10V, V_{DD} = 30V,$ $I_{D} = 10A$	-	4.2	-		
Gate-Drain Charge		\mathbf{Q}_{gd}		-	6.9	-		
Turn-on Delay Time		t _{d(on)}		-	6.4	-	- ns	
Rise Time		tr	$V_{GS} = 10V, V_{DD} = 30V,$ $R_{G} = 3\Omega, I_{D} = 10A$	-	15.3	-		
Turn-off Delay Time		t _{d(off)}		-	25	-		
Fall Time		t _f		-	7.6	-		
Body Diode Reverse Recovery Time		trr		-	26	-	ns	
Body Diode Reverse Recovery Charge		Qrr	- I _F =10A, dI _F /dt=100A/μs	-	45	-	nC	
Drain-Source Body Dio	de Charactei	ristics		•	•	•		
Diode Forward Voltage ⁴		V _{SD}	I _S = 10A, V _{GS} = 0V	-	-	1.2	V	
Continuous Source Current Tc=25°C		Is	-	_	-	20	Α	

Notes:

- 1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C
- 2. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.4mH, I_{AS} =14A
- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 5. This value is guaranteed by design hence it is not included in the production test.



Typical Characteristics

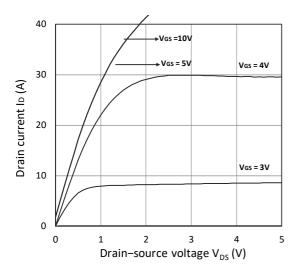


Figure 1. Output Characteristics

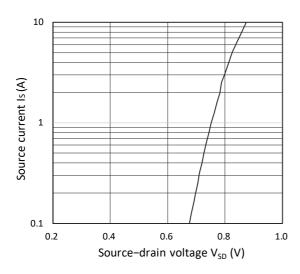


Figure 3. Forward Characteristics of Reverse

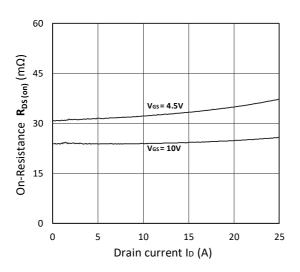


Figure 5. $R_{DS(ON)}$ vs. I_D

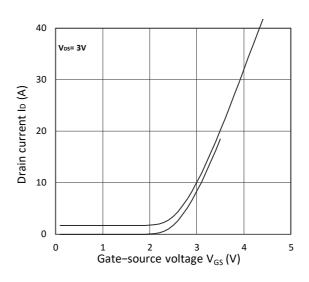


Figure 2. Transfer Characteristics

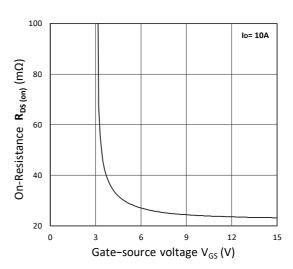


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

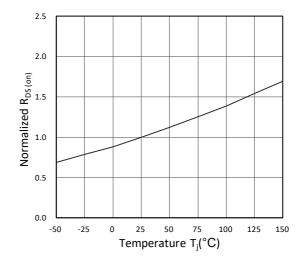
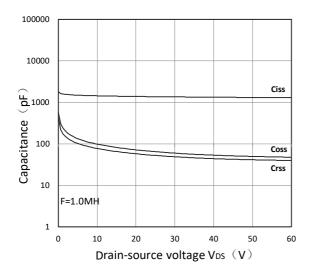


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

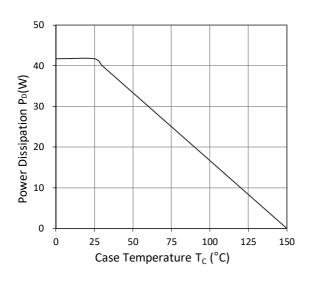




Oge = 30V | IDE = 10A | Oge = No. Solve | Oge =

Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics



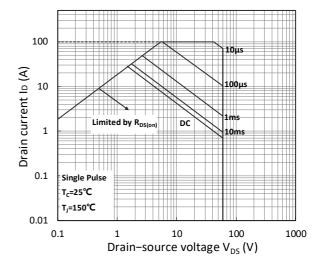


Figure 9. Power Dissipation

Figure 10. Safe Operating Area

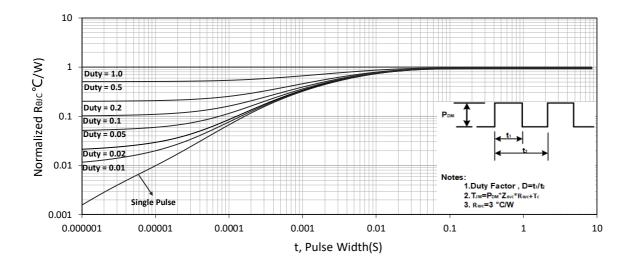
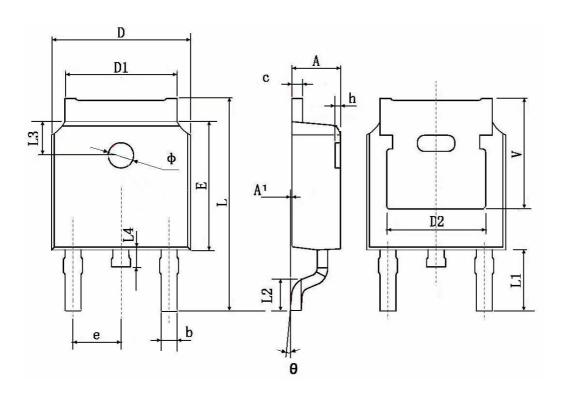


Figure 11. Normalized Maximum Transient Thermal Impedance



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		

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